

MODEL NO. :	TM030LDHT1
ISSUED DATE:	2013-08-01
VERSION :	Ver 2.5
•	

□Preliminary Specification■ Final Product Specification

Customer:

Approved by	Notes

### **SHANGHAI TIANMA Confirmed:**

prepared by	Checked by	Approved by

This technical specification is subjected to change without notice



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## **Record of Revision**

Rev	Issued Date	Description	Editor
2.0	2010-11-08	Final Product Specification	XING.NIE
2.1	2012-02-06	Change the Viewing Direction at page 4 and 20	LONGPING.DENG
2.2	2012-02-20	Chang Input/Output terminals	LONGPING.DENG
2.3	2012-05-08	Chang mechanical drawing	LONGPING.DENG
2.4	2012-07-25	Change Optical characteristics	LONGPING.DENG
2.5	2013-08-01	Add power consumption at page 7	Fen.He



## 1 General specifications

	Fe	Spec		
	Size		3.0 inch	
	Resolutio	n	240(RGB) X 400	
	Interface		RGB+3SPI/CPU	
	Color De	oth	262K	
	Technolo	gy type	a-si TFT	
Diamless Chas	Pixel pitc	h (mm)	0.162x0.162	
Display Spec.	Pixel Cor	figuration	R.G.B. Vertical Stripe	
	Display M	lode	ECB Mode Transflective	
	Surface T	reatment(Up Polarizer)	Clear type (3H)	
	Surface T	reatment(TSP)	Without TSP	
	Viewing [	Direction	6 o'clock	
	Gray Sca	le Inversion Direction	12 o'clock	
	DIM.	LCM (W x H x D) (mm)	47.28x76.4x2.4	
<b>.</b>	Active Are	ea(mm)	38.88x 64.8	
Mechanical Characteristics	With /Wit	hout TSP	Without TSP	
	Weight (g	ram)	18.25g	
	LED Num	nbers	4LEDs (serial)	

Note 1 : Viewing direction for best image quality is different from TFT definition, there is a 180 degree shift.

Note 2: Requirements on Environmental Protection: Q/S0002



# 2 Input/Output terminals

Pin	Symbol (CPU)	Symbol (RGB)	I/O	Description	Remark
1	GND	GND		Ground	
2	LED-K	LED-K		Power supply for LED(Low voltage)	
3	LED-A2	LED-A2		Power supply for LED(High voltage2)	
4	LED-A1	LED-A1		Power supply for LED(High voltage1)	
5	GND	GND		Ground	
6	GND	GND		Ground	
7	/RESET	/RESET	I	RESET serial(Low active)	
8	GND	GND		Ground	
9	DB17	R5	I/O	CPU:Data bus serial(MSB) RGB:RED data signal(MSB)	
10	DB16	R4	I/O	CPU:Data bus serial RGB:RED data signal	*
11	DB15	R3	I/O	CPU:Data bus serial RGB:RED data signal	
12	DB14	R2	I/O	CPU:Data bus serial RGB:RED data signal	
13	DB13	R1	I/O	CPU:Data bus serial RGB:RED data signal	
14	DB12	R0	I/O	//O CPU:Data bus serial RGB:RED data signal(LSB)	
15	DB11	G5	I/O	CPU:Data bus serial RGB:GREEN data signal(MSB)	
16	DB10	G4	I/O	CPU:Data bus serial RGB:GREEN data signal	
17	DB9	G3	1/0	CPU:Data bus serial RGB:GREEN data signal	
18	DB8	G2	I/O	CPU:Data bus serial RGB:GREEN data signal	
19	DB7	G1	I/O	CPU:Data bus serial RGB:GREEN data signal	
20	DB6	G0	I/O	CPU:Data bus serial RGB:GREEN data signal(LSB)	
21	DB5	B5	I/O	CPU:Data bus serial RGB:BLUE data signal(MSB)	
22	DB4	B4	I/O	CPU:Data bus serial RGB:BLUE data signal	
23	DB3	B3	I/O	CPU:Data bus serial RGB:BLUE data signal	
24	DB2	B2	I/O	CPU:Data bus serial RGB:BLUE data signal	
25	DB1	B1	I/O	CPU:Data bus serial RGB:BLUE data signal	
26	DB0	В0	I/O	CPU:Data bus serial RGB:BLUE data signal(LSB)	



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CPU: Ground RGB: Serial data input pin						
OPEN SDO O CPU: not use. leave open or to GND/VCCIO RGB: Serial data output pin  PRO NC I CPU: read signal and read data. RGB: NO connect  CPU: write signal and write data. RGB: NO connect  CPU: Data / Command Selection pin. RGB: Serial Clock signal  CPU: Ground RGB: A data ENABLE signal  CPU: Ground RGB: Frame synchronizing signal  TE TE O CPU: Ground RGB: Pixel clock signal  CPU: Ground RGB: Frame synchronizing signal  CPU: Ground RGB: Frame synchronizing signal  CPU: Ground RGB: Frame synchronizing signal  CPU: Ground RGB: Pixel clock signal  CPU: Ground RGB: Pixel clock signal  CPU: Tearing effect output. RGB: Not used, please open this pin.  WCCIO VCCIO P I/O Pad and Digital power supply  VCC VCC P Analog power supply  MIMO/1D IMO/1D I System interface select. Note2  IM1 IM1 IM1 I System interface select. Note2  IM2 IM2 IM2 I System interface select. Note2  IM3 GND GND Ground	27	GND	SDI	ı		
Second	28	OPEN	SDO	0	CPU: not use. leave open or to GND/VCCIO	
RGB: NO connect   RGB: Serial Clock signal   RGB: A data ENABLE signal   RGB: A data ENABLE signal   RGB: A data ENABLE signal   RGB: Frame synchronizing signal   RGB: Pixel clock signal   RGB: Pixel clock signal   RGB: Not used, please open this pin.   RGB: Not used, please open this	29	/RD	NC	I		
SCL   RGB: Serial Clock signal   RGB: Serial Clock signal   RGB: Serial Clock signal   RGB: A data ENABLE signal   CPU: Ground   RGB: A data ENABLE signal   CPU: Ground   RGB: Frame synchronizing signal   RGB: Frame synchronizing signal   CPU: Ground   RGB: Frame synchronizing signal   RGB: Frame synchronizing signal   CPU: Ground   RGB: Pixel clock signal   RGB: Pixel clock signal   RGB: Not used, please open this pin.   RGB: Not used, plea	30	/WR	NC	I		
GND   ENABLE   I   CPU: Ground   RGB: A data ENABLE signal   CPU: Ground   RGB: Frame synchronizing signal   CPU: Ground   RGB: Pixel clock signal   CPU: Tearing effect output.   RGB: Not used, please open this pin.   RGB:	31	RS	SCL	I	•	
GND ENABLE I CPU: Ground RGB: A data ENABLE signal  GND VSYNC I CPU: Ground RGB: Frame synchronizing signal  GND HSYNC I CPU: Ground RGB: Frame synchronizing signal  GND DOTCLK I CPU: Ground RGB: Frame synchronizing signal  TE TE O CPU: Ground RGB: Pixel clock signal  CPU: Ground RGB: Pixel clock signal  CPU: Tearing effect output. RGB: Not used, please open this pin.  WCCIO VCCIO P I/O Pad and Digital power supply  VCC VCC P Analog power supply  MIMO/1D IMO/1D I System interface select.  Note2  IM1 IM1 IM1 I System interface select.  Note2  GND GND GND Ground  Ground	32	/CS	CS	ı	Chip select signal.	
34GNDVSYNCICPU: Ground RGB: Frame synchronizing signal35GNDHSYNCICPU: Ground RGB: Frame synchronizing signal36GNDDOTCLKICPU: Ground RGB: Pixel clock signal37TETEOCPU: Tearing effect output. RGB: Not used, please open this pin.38VCCIOVCCIOPI/O Pad and Digital power supply39VCCVCCPAnalog power supply40IM0/1DIM0/1DISystem interface select.Note241IM1IM1ISystem interface select.Note242IM2IM2ISystem interface select.Note243GNDGNDGround44GNDGNDGround	33	GND	ENABLE	I	CPU: Ground	
GND	34	GND	VSYNC	I	CPU: Ground	
36GNDDOTCLKICPU: Ground RGB: Pixel clock signal37TETEOCPU: Tearing effect output. RGB: Not used, please open this pin.38VCCIOVCCIOPI/O Pad and Digital power supply39VCCVCCPAnalog power supply40IM0/1DI M0/1DISystem interface select.Note241IM1IM1ISystem interface select.Note242IM2IM2ISystem interface select.Note243GNDGNDGround44GNDGNDGround	35	GND	HSYNC	I	CPU: Ground	
RGB: Not used, please open this pin.	36	GND	DOTCLK	I	CPU: Ground	
39     VCC     VCC     P     Analog power supply       40     IM0/1D     IM0/1D     I     System interface select.     Note2       41     IM1     IM1     I     System interface select.     Note2       42     IM2     IM2     I     System interface select.     Note2       43     GND     GND     Ground       44     GND     GND     Ground	37	TE	TE	0		
40 IM0/1D IM0/1D I System interface select. Note2 41 IM1 IM1 I System interface select. Note2 42 IM2 IM2 I System interface select. Note2 43 GND GND Ground 44 GND GND Ground	38	VCCIO	VCCIO	Р	I/O Pad and Digital power supply	
41 IM1 IM1 I System interface select. Note2 42 IM2 IM2 I System interface select. Note2 43 GND GND Ground 44 GND GND Ground	39	VCC	VCC	Р	Analog power supply	
42IM2I M2I System interface select.Note243GNDGNDGround44GNDGNDGround	40	IM0/1D	IM0/1D	I	System interface select.	Note2
43 GND GND Ground  44 GND GND Ground	41	IM1	IM1	1 (	System interface select.	Note2
44 GND GND Ground	42	IM2	IM2	\	System interface select.	Note2
	43	GND	GND		Ground	
45 GND GND Ground	44	GND	GND		Ground	
	45	GND	GND		Ground	

Note1: P: Power/GND; I: input pin; O: output Note2:System interface select

IM2	IM1	IM0	Interface
0	0	0	8080 MCU 18-bits Parallel II
0	1	0	8080 MCU 16-bits Parallel II
0	0	1	8080 MCU 9-bits Parallel II
0	1	1	8080 MCU 8-bits Parallel II
1	0	ID	3-wire Serial interface
1	1	0	4-wire Serial interface(1)
1	1	1	SPI(2),HSIM Interface



## 3 Absolute maximum ratings

Item	Symbol	MIN	MAX	Unit	Remark
Supply Voltage	VCC	-0.3	4.6	V	
Supply Voltage	VCCIO	-0.3	4.6	V	
Input voltage	D[17: 0], CS, RD, WR, RS/SCL, SDI, VSYNC, HSYNC, DOTCLK, ENABLE, BS[2:0]	-0.3	VCC+0.3	V	
Back Light Forward Current	I <sub>LED</sub>		25	mA	For each LED
Operating Temperature	$T_OPR$	-20	70	$^{\circ}$	
Storage Temperature	T <sub>STG</sub>	-30	80	$^{\circ}$ C	

(GND=0, Ta = 25°C)

## 4 LCD module electrical characteristics

#### 4.1 Driving TFT LCD Panel

Item		Symbol	MIN	TYP	MAX	Unit	Remark
Supply \	/oltage	VCC	2.5	2.8	3.3	V	
Supply \	/oltage	IOVCC	1.65	2.8	3.3	V	
Input Signal	Low Level	V <sub>IL</sub>	-0.3		0.2* IOVCC	٧	
Voltage	High Level	V <sub>IH</sub>	0.8* IOVCC		IOVCC	٧	
Output Signal	Low Level	V <sub>OL</sub>	-0.3		0.3* IOVCC	>	
Voltage	High Level	V <sub>ОН</sub>	0.7* IOVCC		IOVCC	<b>V</b>	
(Panel+LSI) Power Consumption		Black Mode (60Hz)		49.5		mW	
Fower Const	implion	Standby Mode		0.132		mW	

(GND=0,Ta=25°C)

### 4.2 Backlight Unit Driving Condition

(GND=0,Ta=25°C)

Parameter	Symbol	MIN	TYP	MAX	Unit	Remark
Forward Current	I <sub>F</sub>	-	20	-	mA	Note 1
Forward Voltage	V <sub>F</sub>	-	12.8	-	V	Note 2
Backlight Power	W <sub>BL</sub>	-	256	-	mW	

Note 1: The LED driving condition is defined for each LED module.

Note 2: Backlight unit driving must depend on Forward Current setting.

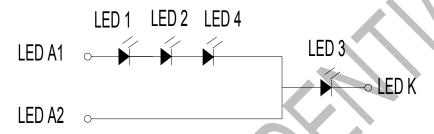
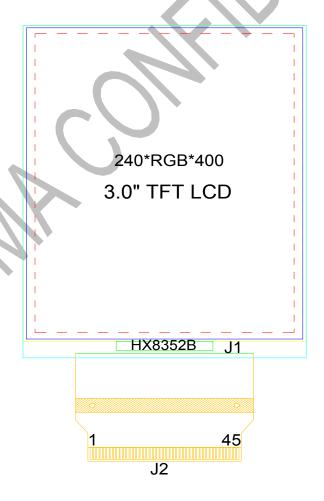


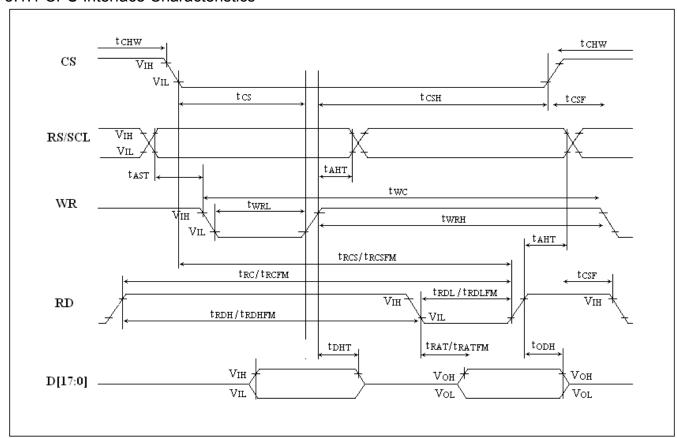
Fig.4-1 LED connection of backlight

### 4.3 Block Diagram



#### 5.1 CPU interface mode

#### 5.1.1 CPU Interface Characteristics



**CPU Interface Characteristics** 



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TM030LDHT1 V2.5

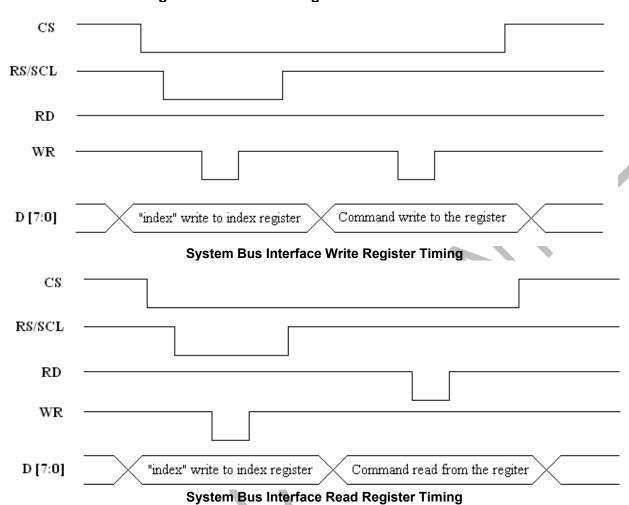
5.1.2 CPU Interface Timing Parameters

Normal Write Mode (IOVCC=1.65~3.3V, VCC=2.3~3.3V)

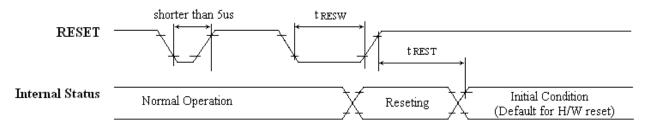
Cianal	Cymphol	Doromotor		Spec.		Description	
Signal	Symbol	Parameter	Min.	Max.	Unit	Description	
RS/SCL	tast taht	Address setup time Address hold time(Write/Read)	10 10	-	ns	-	
CS	tchw tcs trcs trcsfm tcsf tcsh	Chip select "H" pulse width Chip select setup time (Write) Chip select setup time (Read ID) Chip select setup time (Read FM) Chip select wait time(Write/Read) Chip select hold time	0 35 100 100 10 10	-	ns		
WR	twc twr twrL	Write cycle Control pulse "H" duration Control pulse "L" duration	100 20 20	-	ns	-	
RD	t <sub>RC</sub> t <sub>RDH</sub> t <sub>RDL</sub>	Read cycle (ID) Control pulse "H" duration (ID) Control pulse "L" duration (ID)	150 40 50	X	ns	When read ID data	
RD	t <sub>RCFM</sub> Read cycle (FM) t <sub>RDHFM</sub> Control pulse "H" duration (FM) t <sub>RDLFM</sub> Control pulse "L" duration (FM)		250 50 150		ns	When read from frame memory	
D[17:0]	t <sub>dst</sub> t <sub>dht</sub> t <sub>rat</sub> t <sub>ratfm</sub> t <sub>odh</sub>	Data setup time Data hold time Read access time (ID) Read access time (FM) Output disable time	20 20 - - 20	- 70 100 80	ns	For maximum $C_L=30pF$ For minimum $C_L=8pF$	

**CPU Interface Timing Parameters** 

#### 5.1.3 CPU Interface Register write/read timing



### 5.2 Reset Timing



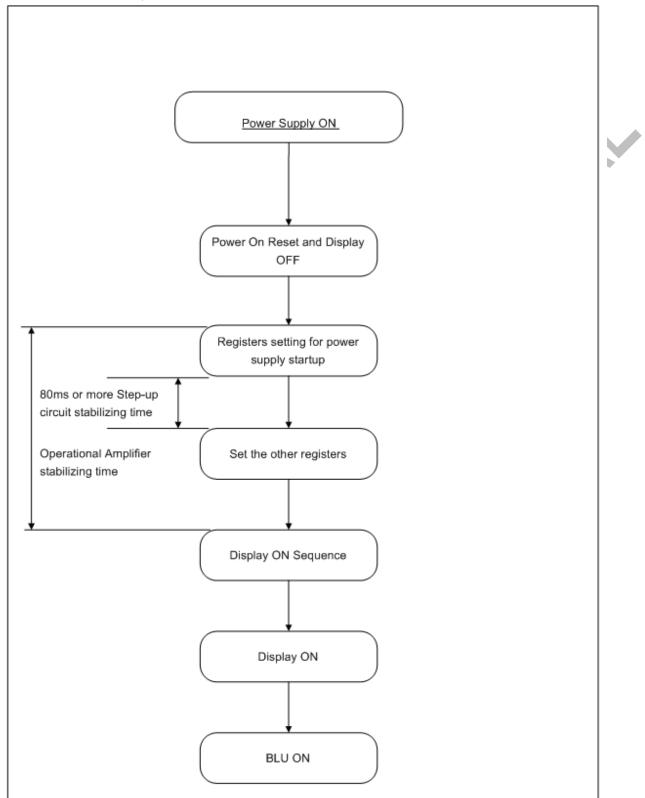
**Reset timing** 

**Reset input timing** 

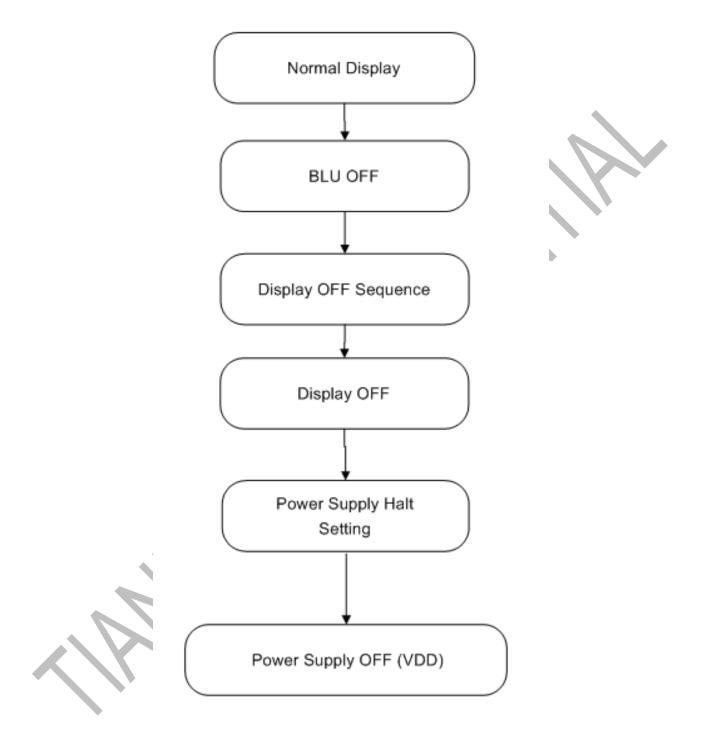
Cymbol	Doromotor	Related	ed Spec.			Note	Unit
Symbol	Parameter	Pins Min.		Тур.	Max.	Note	Unit
t <sub>RESW</sub>	Reset low pulse width	RESET	10	-	-		us
trest	Reset complete time	-	-		5	When reset applied during "Sleep In mode"	ms
		-		-	120	When reset applied during "Sleep Out mode"	ms

### POWER ON/OFF SEQUENCE

#### 6.1 POWER ON SEQUENCE



6.2 POWER OFF





## Optical characteristics

### 7.1 Driving the backlight condition

Ta=25°C

Item		Symbol	Condition	Min	Тур.	Max.	Unit	Remark
		⊖Т		-	55	60		Note 2
View Angles	View Angles		CR≧10	-	40	45	Degree	
view Angles				-	40	45		
		$\theta$ R		-	45	50		
Contrast Ratio		CR	θ=0°	80	100	-		Note1 Note3
Response Tim	Danasa Tima		<b>25</b> ℃		35		ms	Note1
ixesponse rin		Toff	250	-	35		1115	Note4
	White	Wx	θ=0°	0.25	0.30	0.35		Note5,
		Wy		0.27	0.32	0.37		Note1
	Red	Rx		0.52	0.57	0.62		
Chromaticity		Ry		0.27	0.32	0.37		
Chilomaticity	0	Gx	0-0	0.28	0.33	0.38		
	Green	Gy		0.43	0.48	0.53		
	Blue	Вх		0.11	0.16	0.21		
		Ву		0.09	0.14	0.19		
Luminance		L	)	110	130	-	cd/m <sup>2</sup>	Note1 Note7

### 7.2 Not Driving the backlight condition

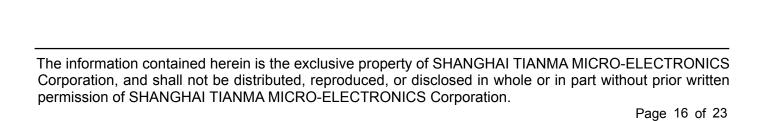
Ta=25°C

Item		Symbol	Condition	Min	Тур.	Max.	Unit	Remark
		θТ			60	-		
Viou Angles		⊖В	CD > 10	-	60	-	Dagge	
View Angles		θL	CR≧10 -	-	55	-	Degree	Note 2
		$\theta$ R		-	60	-		
Contrast Ratio		CR	θ=0°	-	8	_		Note1
oonaast raas		OIT 0	0 0					Note3
Response Time	Daaranaa Tiraa		- 25℃		25		me	Note1
Response Time		Toff		-	25	_	ms	Note4
Chromaticity	\\/hito	Х	θ=0°	0.26	0.31	0.36		Note5,
Chromaticity	White	у	0 =0	0.28	0.33	0.38		Note1

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Luminance	L	110	130	-	cd/m <sup>2</sup>	Note1 Note7
Reflection ratio			6.85%			

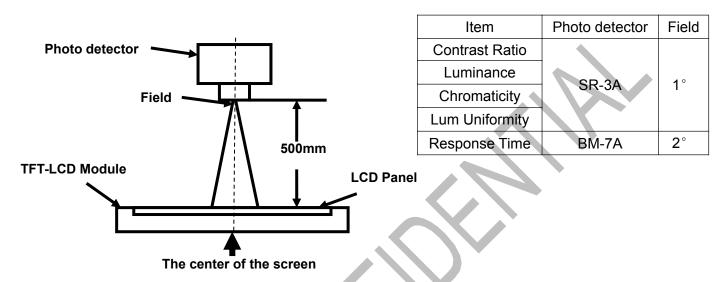
#### **Test Conditions:**

- 1. VDD=2.8V, I<sub>L</sub>=20mA( LED current), the ambient temperature is 25℃.
- 2. The test systems refer to Note 1, Note 2 and Note 8.

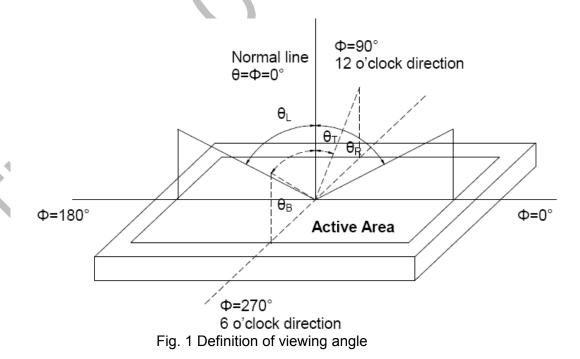


Note 1: Definition of optical measurement system.

The optical characteristics should be measured in dark room. After 5 minutes operation, the optical properties are measured at the center point of the LCD screen. All input terminals LCD panel must be ground when measuring the center area of the panel.



Note 2: Definition of viewing angle range and measurement system. viewing angle is measured at the center point of the LCD by CONOSCOPE(ergo-80).



Note 3: Definition of contrast ratio

Contrast ratio (CR) = Luminance measured when LCD is on the "White" state

Luminance measured when LCD is on the "Black" state

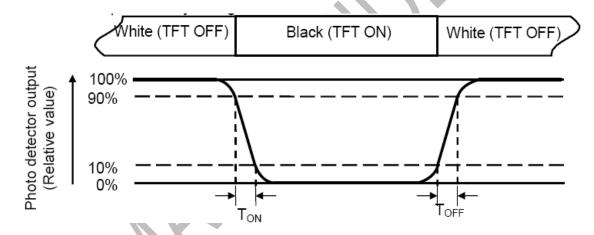
"White state ": The state is that the LCD should driven by Vwhite.

"Black state": The state is that the LCD should driven by Vblack.

Vwhite: To be determined Vblack: To be determined.

### Note 4: Definition of Response time

The response time is defined as the LCD optical switching time interval between "White" state and "Black" state. Rise time (TON) is the time between photo detector output intensity changed from 90% to 10%. And fall time (TOFF) is the time between photo detector output intensity changed from 10% to 90%.



Note 5: Definition of color chromaticity (CIE1931)

Color coordinates measured at center point of LCD.

#### Note 6: Definition of Luminance Uniformity

Active area is divided into 9 measuring areas (Refer Fig. 2). Every measuring point is placed at the center of each measuring area.

Luminance Uniformity(U) = Lmin/Lmax

L-----Active area length W----- Active area width

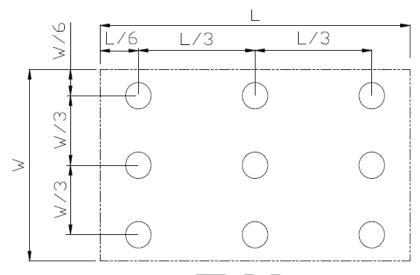


Fig. 2 Definition of uniformity

Lmax: The measured maximum luminance of all measurement position.

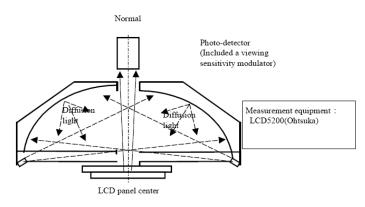
Lmin: The measured minimum luminance of all measurement position.

### Note 7: Definition of Luminance:

Measure the luminance of white state at center point.

### Note 8: Definition of Reflectance measurement system

Note 5) Reflectance is defined as follows:





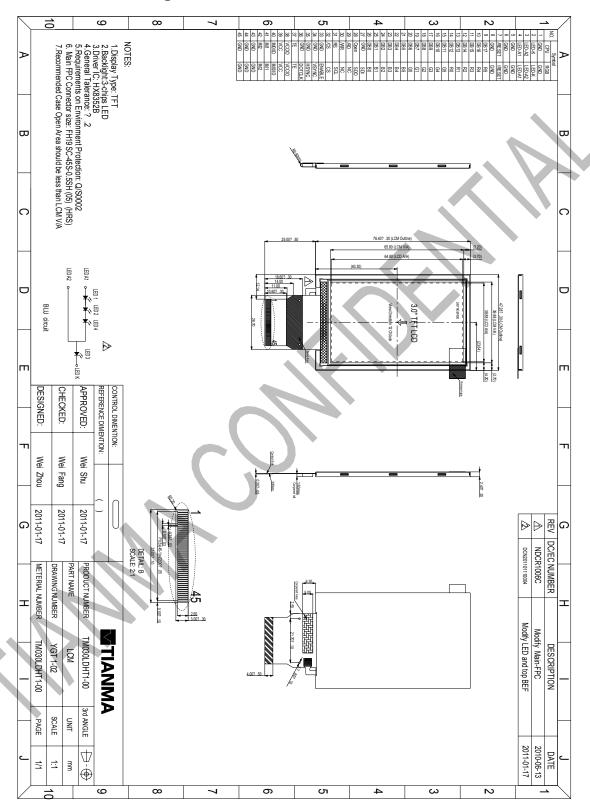
## B Environmental / Reliability tests

No	Test Item	Condition	Remarks
1	High Temperature Operation		Note1 IEC60068-2-2,GB2423.2
2	Low Temperature Operation	Ta=-20°ℂ, 240hrs	IEC60068-2- GB2423.1
3	High Temperature Storage		IEC60068-2-2 GB2423.2
4	Low Temperature Storage	Ta=-30°ℂ , 240hrs	IEC60068-2-1 GB2423.1
5	High Temperature & High Humidity Storage	+40°C, 90% RH max,240 hours	Note2 IEC60068-2-78 GB/T2423.3
6	Thermal Shock (Non-operation)	-30°C 30 min~+70°C 30 min, Change time:5min, 20 Cycle	Start with cold temperature, End with high temperature, IEC60068-2-14,GB2423.22
7	Electro Static Discharge (Operation)	C=150pF, R=330 $\Omega$ , 5points/panel Air:± 8KV, 5times; Contact:± 4KV, 5 times; (Environment: 15 $^{\circ}$ C $\sim$ 35 $^{\circ}$ C, 30% $\sim$ 60%, 86Kpa $\sim$ 106Kpa)	IEC61000-4-2 GB/T17626.2
8	Vibration (Non-operation)	Frequency range:10~55Hz, Stroke:1.5mm Sweep:10Hz~55Hz~10Hz 1 hours for each direction of X.Y.Z.(3 hours for total)	IEC60068-2-6 GB/T2423.10
9	Shock (Non-operation)	60G 6ms, $\pm$ X, $\pm$ Y, $\pm$ Z 3times for each direction	IEC60068-2-27 GB/T2423.5
10	Package Drop Test	Height: 80 cm , 1 corner, 3 edges, 6 surfaces	IEC60068-2-32 GB/T2423.8

Note1: Ts is the temperature of panel's surface.

Note2: Ta is the ambient temperature of sample.

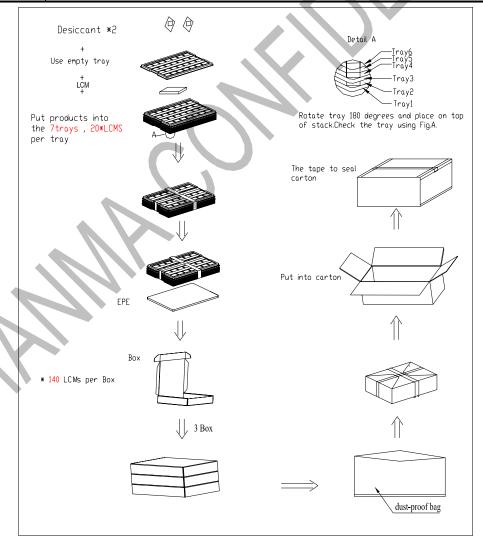
### 9 Mechanical drawing





# 10 Packing drawing

No	Item	Model (Material)	Dimensions(mm)	Unit Weight(Kg)	Quantity	Remark
1	LCM module	TM030LDHT1-00	47.28x76.40 x2.40	0.01825	420	
2	Tray	PET(Transmit)	485 x330 x13.8	0.170	24	Anti-stati c
3.	EPE	EPE	485 x330 x5	0.183	3	
4	Anti-static bag	PE	700x545	0.046	1	
5	BOX	Corrugated Paper	520x345x70	0.3879	3	
6	Desiccant	Desiccant	45 x35	0.002	6	
7	Carton	Corrugated Paper	530x351x226	1.01	1	
8	Total weight		15.25±5%			



#### 11 Precautions for use of LCD modules

- 11.1Handling Precautions
- 11.1.1 The display panel is made of glass. Do not subject it to a mechanical shock by dropping it from a high place, etc.
- 11.1.2 If the display panel is damaged and the liquid crystal substance inside it leaks out, be sure not to get any in your mouth, if the substance comes into contact with your skin or clothes, promptly wash it off using soap and water.
- 11.1.3 Do not apply excessive force to the display surface or the adjoining areas since this may cause the color tone to vary.
- 11.1.4 The polarizer covering the display surface of the LCD module is soft and easily scratched. Handle this polarizer carefully.
- 11.1.5 If the display surface is contaminated, breathe on the surface and gently wipe it with a soft dry cloth. If still not completely clear, moisten cloth with one of the following solvents:
  - Isopropyl alcohol。
  - Ethyl alcohol

Solvents other than those mentioned above may damage the polarizer. Especially, do not use the following:

- Water
- Ketone
- Aromatic solvents
- 11.1.6 Do not attempt to disassemble the LCD Module.
- 11.1.7 If the logic circuit power is off, do not apply the input signals.
- 11.1.8 To prevent destruction of the elements by static electricity, be careful to maintain an optimum work environment.
- 11.1.8.1 Be sure to ground the body when handling the LCD Modules.
- 11.1.8.2 Tools required for assembly, such as soldering irons, must be properly ground.
- 11.1.8.3 To reduce the amount of static electricity generated, do not conduct assembly and other work under dry conditions.
- 11.1.8.4 The LCD Module is coated with a film to protect the display surface. Be care when peeling off this protective film since static electricity may be generated.
  - 11.2 Storage precautions
- 11.2.1 When storing the LCD modules, avoid exposure to direct sunlight or to the light of fluorescent lamps.
- 11.2.2 The LCD modules should be stored under the storage temperature range. If the LCD modules will be stored for a long time, the recommend condition is:

Temperature :  $0^{\circ}$  ~ 40 ° Relatively humidity: ≤80%

- 11.2.3 The LCD modules should be stored in the room without acid, alkali and harmful gas.
  - 11.3 Transportation Precautions:

The LCD modules should be no falling and violent shocking during transportation, and also should avoid excessive press, water, damp and sunshine.